

L Number	Hits	Search Text		Time stamp
1	4	bump with gold with solder with commonly	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/02/20 09:57
-	1	2000JP-0223623.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 09:00
-	0	JP-0223623\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 09:01
-	1	1999JP-0018852.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 09:29
-	1	2000-631087.NRAN.	DERWENT	2003/02/19 09:04
-	2	20020089052.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 10:55
-	1296	(257/690).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 09:33
-	994	(257/668).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 09:33
-	46	((257/690).CCLS.) and ((257/668).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 09:33
-	2244	((257/690).CCLS.) or ((257/668).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 09:33
-	74	((((257/690).CCLS.) or ((257/668).CCLS.)) and elasticity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 09:37
-	12624	surface with mounted and elasticity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 09:38
-	3150	(surface with mounted and elasticity) and (IC chip die semiconductor integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 09:40
-	498	((surface with mounted and elasticity) and (IC chip die semiconductor integrated adj circuit)) and (257/\$.ccls. or 438/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 09:41

-	404	((surf with mounted and elasticity) and (IC chip die semiconductor integrated adj circuit)) and (epoxy and silicone)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 09:41
-	171	((surface with mounted and elasticity) and (IC chip die semiconductor integrated adj circuit)) and (epoxy and silicone)) and (((surface with mounted and elasticity) and (IC chip die semiconductor integrated adj circuit)) and (257/\$.ccls. or 438/\$.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 10:42
-	3	("6137121" "6222967" "6320893").PN.	USPAT	2003/02/19 09:59
-	7	5948991.URPN.	USPAT	2003/02/19 10:14
-	185	((surface with mounted and elasticity) and (IC chip die semiconductor integrated adj circuit)) and (epoxy and silicone)) not (((surface with mounted and elasticity) and (IC chip die semiconductor integrated adj circuit)) and (epoxy and silicone)) and (((surface with mounted and elasticity) and (IC chip die semiconductor integrated adj circuit)) and (257/\$.ccls. or 438/\$.ccls.)))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 10:42
-	0	JP-11238962\$-did..pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 10:55
-	0	JP-11238962\$-did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 10:55
-	2	JP-11238962-\$-did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 11:28
-	396	(257/702).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 11:29
-	46	((257/702).CCLS.) and silicone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 11:54
-	1	"20030003623"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 11:57
-	1	6445074.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 13:52
-	76	silicon adj gel with silicone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:12
-	252	mounted and silicone and (wiring printed)	EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:13

-	133	mounted and silicone and (wiring printed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/02/19 14:18
-	1539	mounted and silicone and bump and (wiring printed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/02/19 14:26
-	466	(mounted and silicone and bump and (wiring printed)) and 257/\$.ccls.	USPAT	2003/02/19 15:06
-	4	("4643526" "6039896" "6108210" "6265782").PN.	USPAT	2003/02/19 14:46
-	524	silicone with resin with gel	USPAT	2003/02/19 15:07
-	0	silicone with elasticity with 3\$mpa	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/02/19 15:28
-	1997	silicone with elasticity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/02/19 15:30
-	4	wiring with gold with plating with wettability	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/02/19 17:14
-	126	(gold tin) with plating with wettability	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/02/19 17:14
-	112	(gold tin) with plating with wettability	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/02/19 17:20
-	7	(gold tin) with bump with wettability	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/02/19 17:22
-	8	(gold tin) with substrate with plating with improve same bump	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/02/19 17:25
-	10	(gold tin) with pad with plating with improve same bump	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/02/19 17:25
-	25	(gold au Sn tin) with pad with plating with improve	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/02/19 17:26
-	15	((gold au Sn tin) with pad with plating with improve) not ((gold tin) with pad with plating with improve same bump)	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/02/19 17:34
-	6	lead with plating with improve with bump	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/02/19 17:37
-	11	wiring with plating with improve with bump	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/02/19 17:38
-	196	wiring with plating with improve	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/02/20 09:56